

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Adrian E. Ong
Title: Chip Testing Within A Multi-chip Semiconductor Package
Application No.: Unknown
Filing Date: Herewith
Examiner: Dipakkumar B. Gandhi (in parent application)
Group Art Unit: 2133 (in parent application)
Confirmation No.: Unknown
Law Office: Sidley Austin Brown & Wood LLP
Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

Dear Sir:

The above-identified patent application is a continuation of co-pending U.S. Patent Application Serial No. 09/666,208, filed on September 21, 2000, entitled "Chip Testing Within A Multi-Chip Semiconductor Package." Please amend the above-identified patent application as follows.